L Number	Hits	Search Text	DB	Time stamp
•	92	(438/71).CCLS.	USPAT;	2002/02/16 17:49
			US-PGPUB;	2002/02/10 17:49
			EPO; JPO;	
			DERWENT;	
-	1007	(438/637).CCLS.	IBM_TDB	2000/00/00
		(100,007),0023.	USPAT;	2002/02/16 14:37
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
•	435	copper and ((438/637).CCLS.)	IBM_TDB	
	.55	copper and (( 130/037).CCL3.)	USPAT;	2002/02/16 14:38
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
-	205	(438/658).CCLS.	IBM_TDB	
	203	(430/030).CCL3.	USPAT;	2002/02/16 15:07
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	200	/470 // FO) CCI C	IBM_TDB	
-	206	(438/659).CCLS.	USPAT;	2002/02/16 15:08
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	461704		IBM_TDB	
-	461794	copper	USP⊼T;	2002/02/16 15:08
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	7.	(/470//50) (616)	IBM_TDB	
•	30	((438/659).CCLS.) and copper	USPĀT;	2002/02/16 15:12
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	0.7	/470 // 7/ ) CCI C	IBM_TDB	
•	93	(438/676).CCLS.	USPAT;	2002/02/16 15:12
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	2.1	conner and //470 //7/) CCI C >	IBM_TDB	
	21	copper and ((438/676).CCLS.)	USPAT;	2002/02/16 15:13
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
-	266	(438/689).CCLS.	IBM_TDB	
	200	(430/007).CCL3.	USPAT;	2002/02/16 15:13
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
-	62	copper and ((438/689).CCLS.)	IBM_TDB	
	O2	copper and ((436/869).CCLS.)	USPAT;	2002/02/16 15:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
-	947	(438/706).CCLS.	IBM_TDB	
	, 13	(130/700/.0013.	USPAT;	2002/02/16 15:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	

-	77	copper and ((438/706).CCLS.)	USPAT; US-PGPUB;	2002/02/16 15:24
	72	(438/707).CCLS.	EPO; JPO; DERWENT; IBM_TDB	
	72	(436/707).CCL3.	USPAT; US-PGPUB; EPO; JPO;	2002/02/16 15:25
-	276	(438/712).CCLS.	DERWENT; IBM_TDB USPAT; US-PGPUB;	2002/02/16 15:26
			EPO; JPO; DERWENT; IBM TDB	
•	54	copper and ((438/712).CCLS.)	USPĀT; US-PGPUB; EPO; JPO;	2002/02/16 15:28
-	4988	copper adj chloride	DERWENT; IBM_TDB USPAT;	2002/02/16 15:28
			US-PGPUB; EPO; JPO; DERWENT; IBM TDB	
•	194290	interconnect	USPAT; US-PGPUB; EPO; JPO;	2002/02/16 15:28
	9855	dry adj etch	DERWENT; IBM_TDB USPAT;	2002/02/16 15:29
			US-PGPUB; EPO; JPO; DERWENT;	
-	40	(copper adj chloride) and interconnect and (dry adj etch)	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/02/16 15:29
-	2	("6153530").PN.	DERWENT; IBM_TDB USPAT;	2002/02/16 15:50
			US-PGPUB; EPO; JPO; DERWENT;	
-	2	("6010603").PN.	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/02/16 17:49
			DERWENT; IBM_TDB	